



RS6- M Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 35.25%	Copper (Cu)	7440-50-8	2,400.820	99.9787	352,415.4
	Phosphorus (P)	7723-14-0	0.024	0.0010	3.5
	Arsenic (As)	7440-38-2	0.024	0.0010	3.5
	Tin (Sn)	7440-31-5	0.024	0.0010	3.5
	Oxygen (O)	7782-44-7	0.012	0.0005	1.8
	Sulfur (S)	7704-34-9	0.288	0.0120	42.3
	Iron (Fe)	7439-89-6	0.016	0.0007	2.3
	Nickel (Ni)	7440-02-0	0.007	0.0003	1.1
	Bismuth (Bi)	7440-69-9	0.048	0.0020	7.0
	Antimony (Sb)	1309-64-4	0.048	0.0020	7.0
	Lead (Pb)	7439-92-1	0.012	0.0005	1.8
	Zinc (Zn)	7440-66-6	0.007	0.0003	1.1
	Total			2,401.33	
Solder Wafer 0.31%	Lead (Pb)	7439-92-1	19.74	92.50	2,897.0
	Tin (Sn)	7440-31-5	1.07	5.00	156.6
	Silver (Ag)	7440-22-4	0.53	2.50	78.3
	Total			21.34	
Chip 0.21%	Silicon (Si)	7440-21-3	14.67	100.00	2,152.7
	Total			14.67	
Molding 64.11%	Silica (SiO ₂)	14808-60-7	3188.42	73.00	468,027.1
	Epoxy resin	29690-82-2	742.51	17.00	108,992.6
	Phenolic resin	9003-35-4	384.36	8.80	56,419.7
	Antimony trioxide(Sb	1309-64-4	30.57	0.70	4,487.9
	Brominated epoxy re	40039-93-8	20.09	0.46	2,949.2
	Carbon Black	1333-86-4	1.75	0.04	256.5
	Total			4,367.70	
Plating 0.12%	Tin (Sn)	7440-31-5	7.44	100.00	1,092.1
	Total			7.44	
Total mass (mg)			6,812.47		

